

## **IN THE CLAIMS:**

The following is a list of all pending claims. Please amend the following claims as follows:

1-30 cancelled.

31. (Presently Amended) A method of underfilling a gap between a multi-sided semiconductor device and a ~~substrate~~ chip carrier on which it is mounted to encapsulate a plurality of electrical connections formed therebetween wherein said chip carrier is mounted on an intermediate mounting substrate, comprising:

forming a channel extending through said intermediate mounting substrate and said chip carrier to said gap ~~between said device and said substrate; and~~

~~leaving said channel open to at least one side of said device to permit access to said device; and~~

dispensing through said channel an under-fill material into said gap ~~adjacent said at least one side of said device through said channel.~~

32. (Original) The method of claim 31 wherein said channel permits the removal of residual flux.

33. (New). the method of claim 31 wherein the chip carrier has a first coefficient of thermal expansion different from a coefficient of thermal expansion of the semiconductor device.

34. (New). The method of claim 31 wherein the chip carrier has a first coefficient of thermal expansion different from a coefficient of thermal expansion of the intermediate mounting substrate.

35. (New) The method of claim 31 wherein the intermediate mounting substrate is adapted for connection to a printed circuit board, said intermediate mounting substrate having a coefficient of thermal expansion different from a coefficient of thermal expansion of the chip carrier and smaller than a coefficient of thermal expansion of the printed circuit board.